

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	shadow adj mask with chamfered	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 23:19
L2	9	etch\$3 with (wire rod screen shadow stencil) near mask\$3 and chamfered	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 23:31
L3	0	etch\$3 with (wire rod screen shadow stencil) near mask\$3 and beveled near opening	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 23:31
L4	0	etch\$3 with (wire rod screen shadow stencil) near mask\$3 and beveled with opening	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 23:31
L5	6	etch\$3 with (wire rod screen shadow stencil) near mask\$3 and beveled	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 23:31
S1	398	(216/12).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 23:18
S2	170	(roughen\$3 texturiz\$3) with (surface substrate wafer workpiece) and (RF adj electrode plasma RIE) and (shadow adj mask plate near (hole aperture opening))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/22 16:14
S3	0	S1 and S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/22 14:57
S4	41	(roughen\$3 texturiz\$3) with (surface substrate wafer workpiece) and (RF adj electrode plasma RIE etch\$3) and (wire rod screen) near mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/22 16:40

S5	50	(roughen\$3 texturiz\$3) with (surface substrate wafer workpiece) and (RF adj electrode plasma RIE etch\$3) and (stencil) near mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/22 16:40
S6	50	(roughen\$3 texturiz\$3) with (surface substrate wafer workpiece) and (plasma RIE etch\$3) and (stencil) near mask	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/22 16:41
S7	2643	etch\$3 with (wire rod screen shadow stencil) near mask\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/26 23:21
S8	1290	etch\$3 with (wire rod screen shadow stencil) near mask\$3	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 15:48
S9	1353	etch\$3 with (wire rod screen shadow stencil) near mask\$3	US-PGPUB; USPAT	OR	OFF	2005/06/23 15:48
S10	1155	etch\$3 with (wire rod screen shadow stencil) adj mask\$3	US-PGPUB; USPAT	OR	OFF	2005/06/23 15:49
S11	167	etch\$3 near (wire rod screen shadow stencil) adj mask\$3	US-PGPUB; USPAT	OR	OFF	2005/06/23 15:49
S12	36	S11 and rough\$5	US-PGPUB; USPAT	OR	OFF	2005/06/23 16:16
S13	52	etch\$3 same (wire plate screen grid mask) with (promote encourage enhance) with (deposit\$3 micromask micro-mask micro adj mask residue)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 16:45
S14	7760	hatakeyama.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 17:41
S15	523	S14 and etch\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 17:41
S16	131	S15 and rough\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 17:41

S17	105	S16 and mask\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 17:42
S18	47	S17 and (rie plasma)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/23 17:42